Dual common-mode rejection differential line receiver

FEATURES

- Excellent common-mode rejection up to high frequencies
- Elimination of source resistance in the common-mode rejection
- Few external components
- High supply voltage ripple rejection
- Low noise
- · Low distortion
- Protected against electrostatic discharge
- AC and DC short circuit safe to ground and $\rm V_{\rm CC}$
- Fast DC settling.

QUICK REFERENCE DATA

APPLICATIONS

- Audio
- Car radio.

GENERAL DESCRIPTION

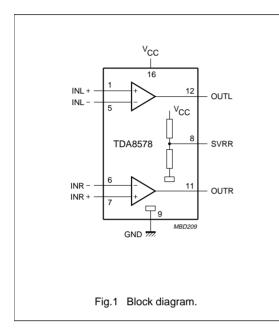
The TDA8578 is a two-channel differential amplifier in a 16 pin DIL or SO package intended to receive line inputs in audio applications requiring a high-level of common-mode rejection. The amplifier has a gain of 0 dB and a low distortion. The device is primarily developed for those car radio applications where long connections between signal sources and amplifiers (or boosters) are necessary and ground noise has to be eliminated.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{cc}	supply voltage		5	8.5	18	V
I _{cc}	supply current	V _{CC} = 8.5 V	-	11	14	mA
G _v	voltage gain		-0.5	0	+0.5	dB
SVRR	supply voltage ripple rejection		-55	-60	-	dB
V _{no}	noise output voltage		-	3.7	5	μV
Z _i	input impedance		100	240	-	kΩ
CMRR	common-mode rejection ratio	$R_s = 0 \Omega$	-	80	-	dB

ORDERING INFORMATION

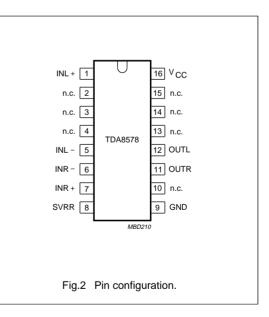
EXTENDED TYPE	PACKAGE				
NUMBER	PINS	PIN POSITION	MATERIAL	CODE	
TDA8578	16	DIL16	plastic	SOT38	
TDA8578T	16	SO16	plastic	SOT109A	

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PINNING

SYMBOL	PIN	DESCRIPTION		
INL+	1	positive input left		
n.c.	2	not connected		
n.c.	3	not connected		
n.c.	4	not connected		
INL-	5	negative input left		
INR-	6	negative input right		
INR+	7	positive input right		
SVRR	8	half supply voltage		
GND	9	ground		
n.c.	10	not connected		
OUTR	11	output right		
OUTL	12	output left		
n.c.	13	not connected		
n.c.	14	not connected		
n.c.	15	not connected		
V _{cc}	16	supply voltage		



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FUNCTIONAL DESCRIPTION

The TDA8578 contains two identical differential amplifiers with a voltage gain of 0 dB. The device is intended to receive line input signals. The device has a very high-level of common-mode rejection and it eliminates ground noise. The common-mode rejection keeps constant up to high frequencies. The gain of the amplifiers is fixed at 0 dB. The inputs have a high-input impedance and the output stage is a class AB stage with a low-output impedance. For a large common-mode rejection also at low frequencies, an electrolytic input capacitor at the negative input pin is advised. The input impedance is relative high, this would result in a large settling time of the DC input voltage. Therefore a quick charge circuit is included that charges the input capacitor within 0.2 s.

All input and output pins are protected against high electrostatic discharge conditions (4000 V, 150 pF, 150 Ω).

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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{cc}	supply voltage	operating	-	18	V
I _{ORM}	repetitive peak output current		-	40	mA
V _{sc}	AC and DC short-circuit safe voltage		-	18	V
T _{stg}	storage temperature		-55	+150	°C
T _{amb}	operating ambient temperature		-40	+85	°C
T _j	junction temperature		-	+150	°C

HANDLING

Inputs and outputs are protected against electrostatic discharges in normal handling. However, to be totally safe, it is desirable to take normal precautions appropriate to handling integrated circuits.

THERMAL RESISTANCE

SYMBOL	PARAMETER	THERMAL RESISTANCE		
R _{th j-a}	from junction to ambient in free air			
	TDA8578 (DIL16)	75 K/W		
	TDA8578T (SO16)	120 K/W		

DC CHARACTERISTICS

 V_{CC} = 8.5 V; T_{amb} = 25 °C; in accordance with test circuit (see Fig.3); unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{cc}	supply voltage		5	8.5	18	V
I _{cc}	supply current		-	11	14	mA
Vo	DC output voltage	note (1)	-	4.3	-	V
t _{set}	DC input voltage settling time		-	0.2	-	S

Note to the DC characteristics

1. The DC output voltage with respect to ground is approximately $0.5V_{cc}$.

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AC CHARACTERISTICS

 V_{CC} = 8.5 V; f = 1 kHz; T_{amb} = 25 °C; in accordance with test circuit (see Fig.3); unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
G _v	voltage gain		-0.5	0	+0.5	dB
α _{cs}	channel separation	$R_s = 5 k\Omega$	70	80	-	dB
$ \Delta G_v $	channel unbalance		-	-	0.5	dB
fL	low frequency roll-off	-1 dB; note ⁽¹⁾	20	-	-	Hz
f _H	high frequency roll-off	-1 dB	20	-	-	kHz
Z _i	input impedance		100	240	-	kΩ
Z _o	output impedance		-	-	10	Ω
V _{i(max)}	maximum input voltage	THD = 1%	-	2	-	V
V _{no}	noise output voltage	$R_s = 0 \Omega$; note ⁽²⁾	-	3.7	5	μV
V _{CM(rms)}	common-mode input voltage (RMS value)		-	-	1	V
CMRR	common-mode rejection ratio	$R_s = 5 k\Omega$	66	70	-	dB
		$R_s = 0 \Omega$; note ⁽³⁾	-	80	-	dB
SVRR	supply voltage ripple rejection	note (4)	55	65	-	dB
		note ⁽⁵⁾	-	60	-	dB
THD	total harmonic distortion	V _i = 1 V	-	0.02	-	%
		$V_i = 1 V;$ f = 20 Hz to 20 kHz	-	-	0.1	%
THD _{max}	total harmonic distortion at maximum output current	$V_{i} = 1 \text{ V}; \text{ R}_{L} = 150 \Omega$	-	-	1	%

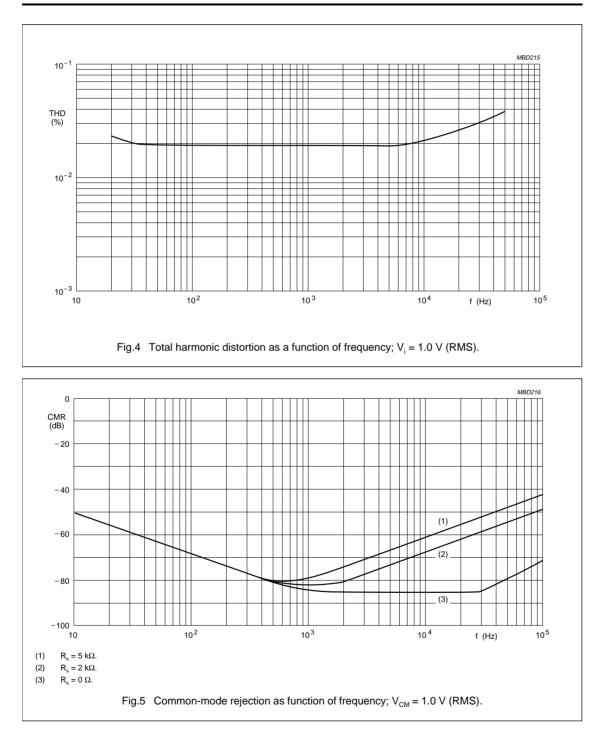
Notes to the AC characteristics

- 1. Frequency response externally fixed by the input coupling capacitors.
- 2. Noise output voltage is measured in a bandwidth of 20 Hz to 20 kHz (unweighted).
- 3. The common-mode rejection ratio is measured at the output, with a voltage source of 1 V (RMS), in accordance with test circuit (see Fig.3), while V_{INL} and V_{INR} are short-circuited. Frequencies between 100 Hz and 100 kHz.
- 4. Ripple rejection is measured at the output, with $R_s = 2 k\Omega$; f = 1 kHz and a ripple amplitude of 2 V (p-p).
- 5. Ripple rejection is measured at the output, with $R_s = 0 \Omega$ up to 2 k Ω and f = 100 Hz to 20 kHz; maximum ripple amplitude of 2V (p-p).

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8.5 V ⊥ 100 nF 220 nF Rs 16 -11-2.2 μF V_{INL} 5 kΩ 12 + || OUTL \sim (V_{CC} 22 µF TDA8578 ſ 47 μF -10-+ ۶ ⁺╢⊢ SVRR 2.2 μF Ţ $^{\rm V}{\rm CM}$ VINR 11 + || OUTR $\sim \oplus$ ~ 0 Rs 220 nF RL RL 10 kΩ 10 kΩ ₽9 _____ 5 kΩ # MBD218 Fig.3 Test circuit.

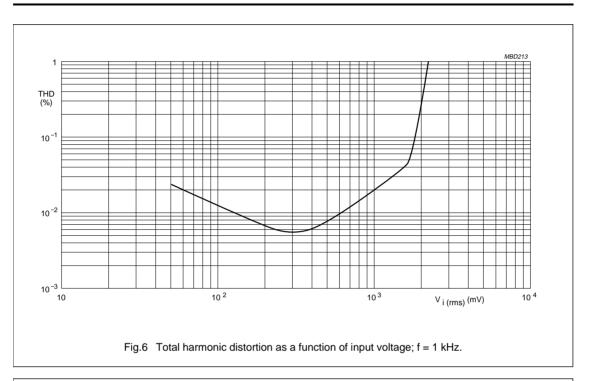
Dual common-mode rejection differential line receiver

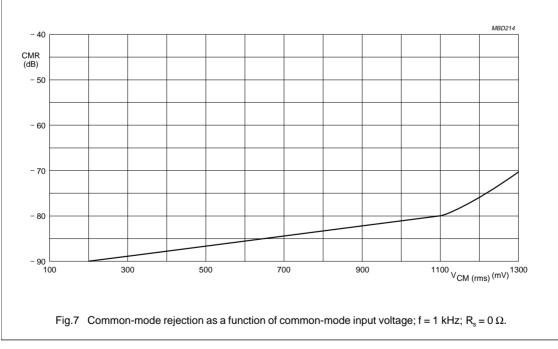


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Dual common-mode rejection differential line receiver



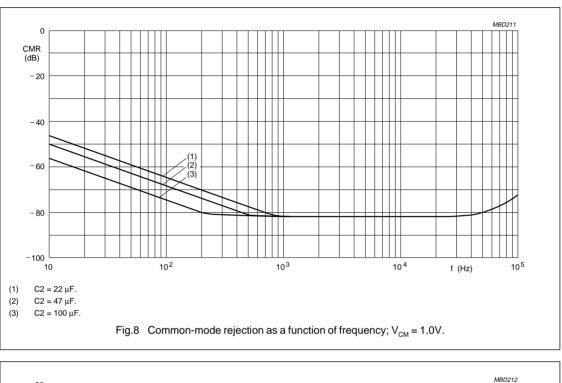


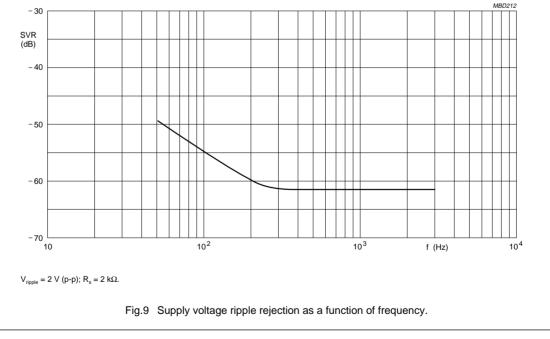
Philips Semiconductors

Preliminary specification

Dual common-mode rejection differential line receiver

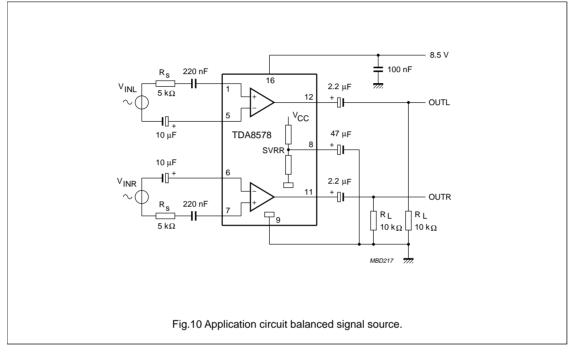
TDA8578





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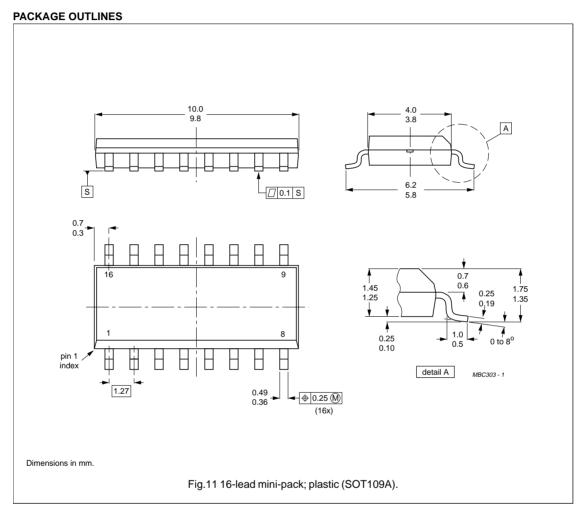
APPLICATION INFORMATION



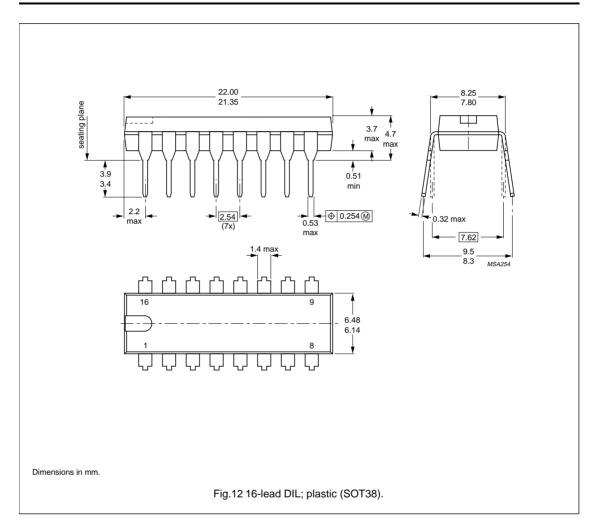
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Dual common-mode rejection differential line receiver

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SOLDERING

Plastic small-outline packages

BY WAVE

During placement and before soldering, the component must be fixed with a droplet of adhesive. After curing the adhesive, the component can be soldered. The adhesive can be applied by screen printing, pin transfer or syringe dispensing.

Maximum permissible solder temperature is 260 °C, and maximum duration of package immersion in solder bath is 10 s, if allowed to cool to less than 150 °C within 6 s. Typical dwell time is 4 s at 250 °C.

A modified wave soldering technique is recommended using two waves (dual-wave), in which, in a turbulent wave with high upward pressure is followed by a smooth laminar wave. Using a mildly-activated flux eliminates the need for removal of corrosive residues in most applications.

BY SOLDER PASTE REFLOW

Reflow soldering requires the solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the substrate by screen printing, stencilling or pressure-syringe dispensing before device placement.

Several techniques exist for reflowing; for example, thermal conduction by heated belt, infrared, and vapourphase reflow. Dwell times vary between 50 and 300 s according to method. Typical reflow temperatures range from 215 to 250 °C°.

Preheating is necessary to dry the paste and evaporate the binding agent. Preheating duration: 45 min at 45 $^\circ$ C.

REPAIRING SOLDERED JOINTS (BY HAND-HELD SOLDERING IRON OR PULSE-HEATED SOLDER TOOL)

Fix the component by first soldering two, diagonally opposite, end pins. Apply the heating tool to the flat part of the pin only. Contact time must be limited to 10 s at up to 300 °C. When using proper tools, all other pins can be soldered in one operation within 2 to 5 s at between 270 and 320 °C. (Pulse-heated soldering is not recommended for SO packages.)

For pulse-heated solder tool (resistance) soldering of VSO packages, solder is applied to the substrate by dipping or by an extra thick tin/lead plating before package placement.

Plastic dual in-line packages

BY DIP OR WAVE

The maximum permissible temperature of the solder is 260 $^{\circ}$ C; this temperature must not be in contact with the joint for more than 5 s. The total contact time of successive solder waves must not exceed 5 s.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified storage maximum. If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

REPAIRING SOLDERED JOINTS

Apply the soldering iron below the seating plane (or not more than 2 mm above it). If its temperature is below $300 \,^{\circ}$ C, it must not be in contact for more than 10 s; if between 300 and 400 $^{\circ}$ C, for more than 5 s.

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Preliminary specification

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